

1.1MHz, 800mA SYNCHRONOUS DC-DC BUCK CONVERTER AP3406A

Pin Configuration

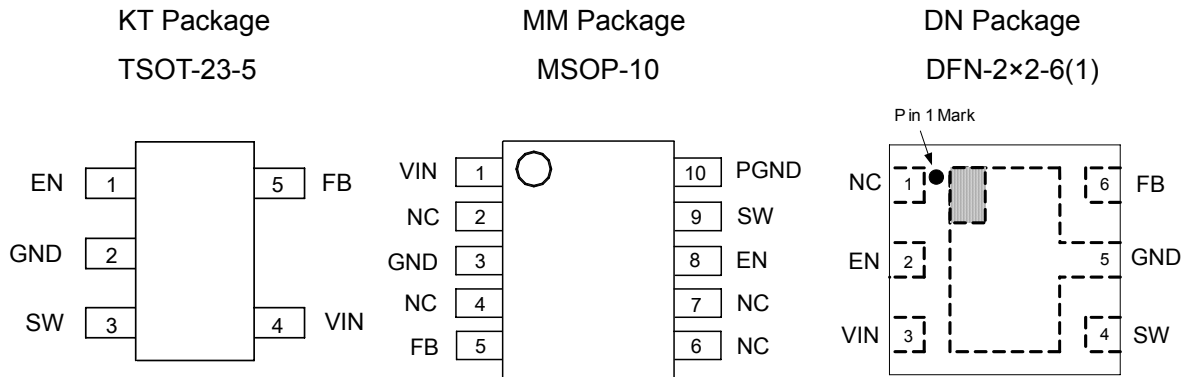


Figure 2. Pin Configuration of AP3406A (Top View)

Pin Description

Pin Number			Pin Name	Function
TSOT-23-5	MSOP-10	DFN-2×2-6(1)		
1	8	2	EN	Control input pin. Forcing this pin above 1.5V enables the IC. Forcing this pin below 0.6V shuts down the IC. When the IC is in shutdown mode, all functions are disabled to decrease the supply current below 1μA
2	3	5	GND	Ground pin
3	9	4	SW	Power switch output pin. Inductor connection to drain of the internal PFET and NFET switches
4	1	3	VIN	Supply input pin. Bypass to GND with a 10μF or greater ceramic capacitor
5	5	6	FB	Feedback pin. Connect it with an external resistor divider network to program the system output voltage
	2, 4, 6, 7	1	NC	No connection
	10		PGND	Power ground pin

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Functional Block Diagram

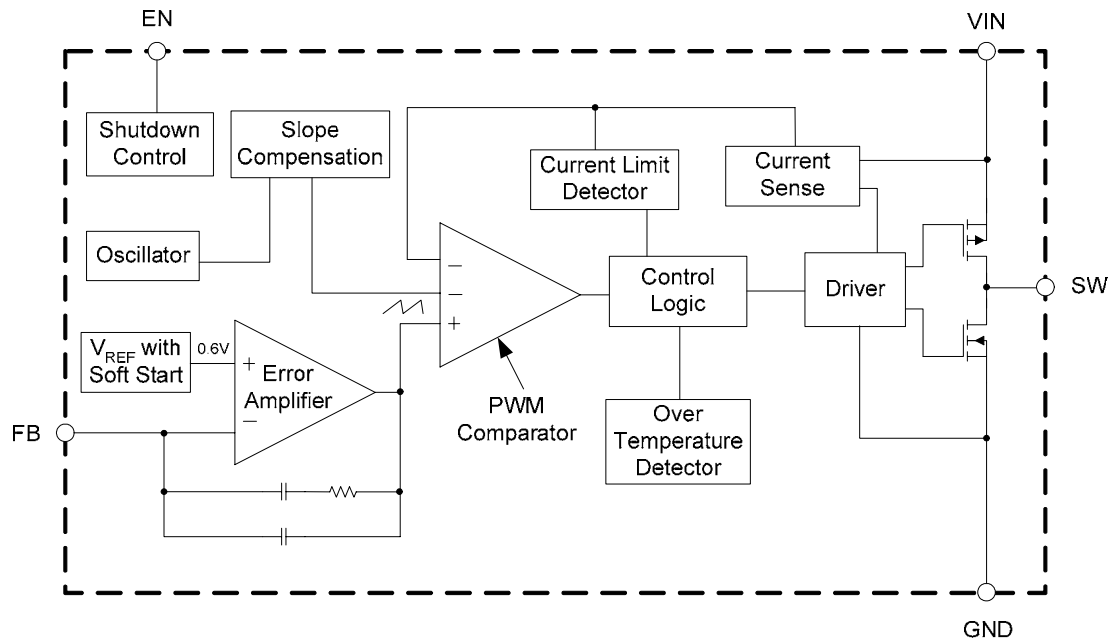


Figure 3. Functional Block Diagram of AP3406A

Ordering Information

AP3406A		-			
Circuit Type					G1: Green
Package					TR: Tape & Reel
KT: TSOT-23-5					ADJ: Adjustable Voltage
MM: MSOP-10					
DN: DFN-2×2-6(1)					

Package	Temperature Range	Part Number	Marking ID	Packing Type
TSOT-23-5	-40 to 85°C	AP3406AKT-ADJTRG1	L2A	Tape & Reel
MSOP-10		AP3406AMM-ADJTRG1	3406AMM-G1	Tape & Reel
DFN-2×2-6(1)		AP3406ADN-ADJTRG1	BA	Tape & Reel

BCD Semiconductor's Pb-free products, as designated with "G1" suffix in the part number, are RoHS compliant and green.

**1.1MHz, 800mA SYNCHRONOUS DC-DC BUCK CONVERTER AP3406A****Absolute Maximum Ratings (Note 1)**

Parameter	Symbol	Value		Unit
Input Voltage	V_{IN}	-0.3 to 6		V
Feedback Voltage	V_{FB}	-0.3 to $V_{IN} + 0.3$		V
EN Pin Voltage	V_{EN}	-0.3 to $V_{IN} + 0.3$		V
SW Pin Voltage	V_{SW}	-0.3 to $V_{IN} + 0.3$		V
Thermal Resistance	θ_{JA}	TSOT-23-5	250	°C/W
		MSOP-10	135	
		DFN-2×2-6(1)	100	
Operating Junction Temperature	T_J	150		°C
Storage Temperature	T_{STG}	-65 to 150		°C
Lead Temperature (Soldering, 10sec)	T_{LEAD}	260		°C

Note 1: Stresses greater than those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “Recommended Operating Conditions” is not implied. Exposure to “Absolute Maximum Ratings” for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
Input Voltage	V_{IN}	2.5	5.5	V
Maximum Output Current	$I_{OUT(MAX)}$	800		mA
Operating Ambient Temperature	T_A	-40	85	°C

**1.1MHz, 800mA SYNCHRONOUS DC-DC BUCK CONVERTER AP3406A****Electrical Characteristics**

$V_{IN} = V_{EN} = 3.6V$, $T_A = 25^\circ C$, unless otherwise specified. Specifications with **boldface type** apply over full operating temperature range from -40 to $85^\circ C$.

Parameters	Symbol	Conditions	Min	Typ	Max	Unit
Supply Current	I_{CC}	$V_{FB} = 0.55V$		400	600	μA
Shutdown Supply Current	I_{SHDN}	$V_{EN} = 0V$, $V_{IN} = 5.5V$		0.01	1	μA
Under Voltage Lockout Threshold	V_{UVLO}	Rising edge		2.27		V
Under Voltage Lockout Hysteresis	V_{HUVLO}			200		mV
Feedback Bias Current	I_{FB}	$V_{FB} = 0.65V$	-50	0.5	50	nA
Feedback Voltage	V_{FB}	$I_{OUT} = 100mA$	0.588/ 0.582	0.600	0.612/ 0.618	V
Maximum Output Current	$I_{OUT(MAX)}$	$V_{IN} = 2.5V$, $V_{OUT} = 0.9V$	800			mA
		$V_{IN} = 3.6V$, $V_{OUT} = 1.2V$	800			
		$V_{IN} = 4.6V$, $V_{OUT} = 3.3V$	800			
Switch Current Limit	I_{LIM}	$V_{FB} = 0.55V$	0.95	1.25		A
Oscillator Frequency	f_{OSC}		0.8	1.1	1.4	MHz
EN Pin Threshold	V_{ENL}				0.6	V
	V_{ENH}		1.5			
EN Pin Input Leakage Current	I_H	$V_{EN} = 3.6V$	-0.1		0.1	μA
	I_L	$V_{EN} = 0V$	-0.1		0.1	μA
Internal PFET On Resistance	$R_{DS(ON)P}$	$I_{SW} = 100mA$		0.44		Ω
Internal NFET On Resistance	$R_{DS(ON)N}$	$I_{SW} = -100mA$		0.29		Ω
Maximum Duty Cycle	D_{MAX}	$V_{FB} = 0.55V$		100		%
Soft-start Time	T_{SS}	$V_{EN} = 0V$ to V_{IN} $I_{OUT} = 50mA$		220		μs
Thermal Shutdown Threshold	T_{OTSD}			160		$^\circ C$
Thermal Shutdown Hysteresis	T_{HYS}			30		$^\circ C$

**1.1MHz, 800mA SYNCHRONOUS DC-DC BUCK CONVERTER AP3406A****Typical Performance Characteristics**

$L=10\mu\text{H}$, $C_{\text{IN}}=C_{\text{OUT}}=10\mu\text{F}$, $T_A=25^\circ\text{C}$, unless otherwise noted.

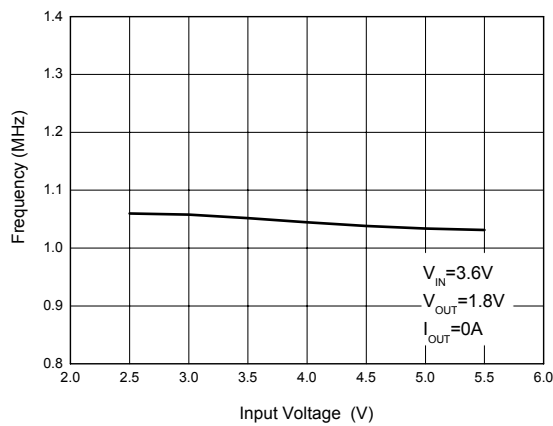


Figure 4. Frequency vs. Input Voltage

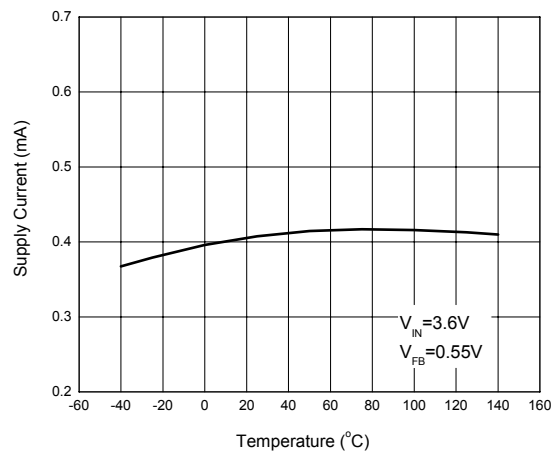


Figure 5. Supply Current vs. Temperature

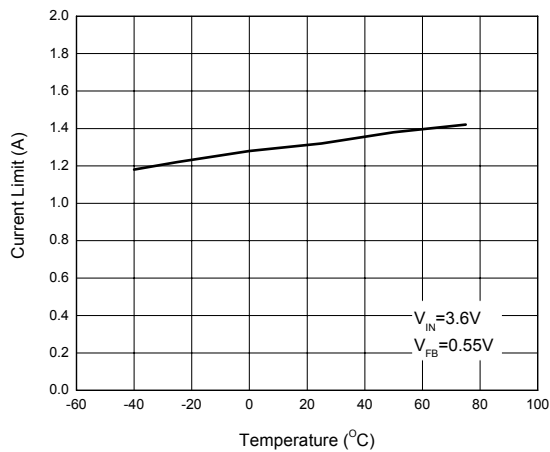
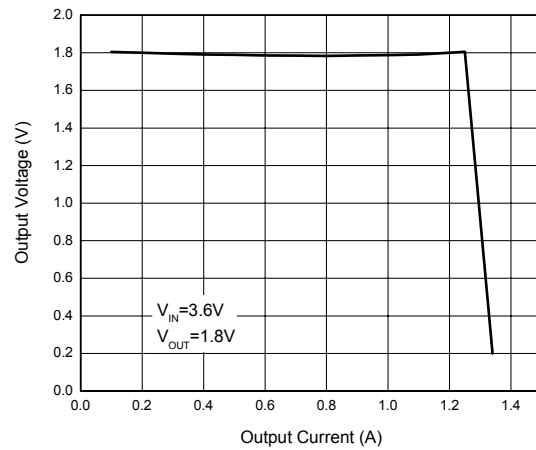
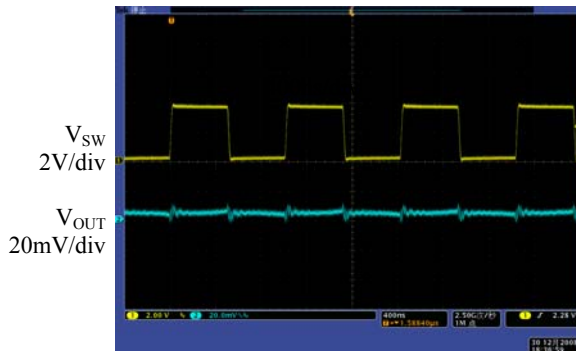


Figure 6. Current Limit vs. Temperature



1.1MHz, 800mA SYNCHRONOUS DC-DC BUCK CONVERTER AP3406A

Typical Performance Characteristics (Continued)



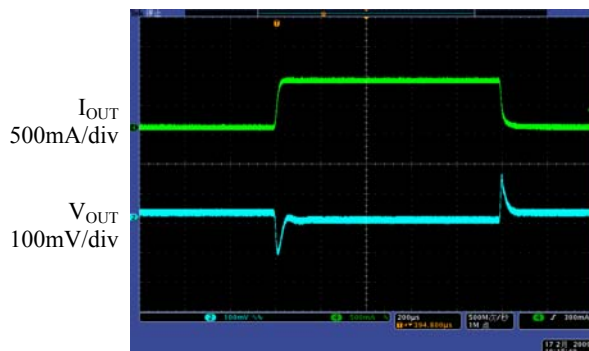
400ns/div

Figure 8. Light Load Operation
($V_{IN}=3.6V$, $V_{OUT}=1.8V$, $I_{OUT}=0mA$)



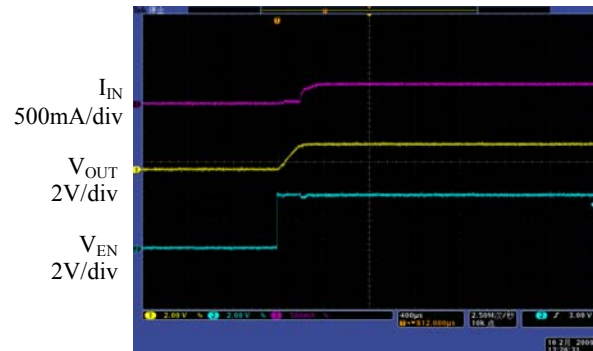
400ns/div

Figure 9. Heavy Load Operation
($V_{IN}=3.6V$, $V_{OUT}=1.8V$, $I_{OUT}=800mA$)



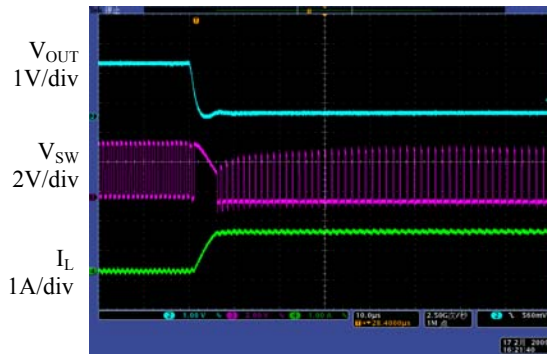
200μs/div

Figure 10. Load Transient
($V_{IN}=3.6V$, $V_{OUT}=1.8V$, $I_{OUT}=0mA$ to $800mA$)



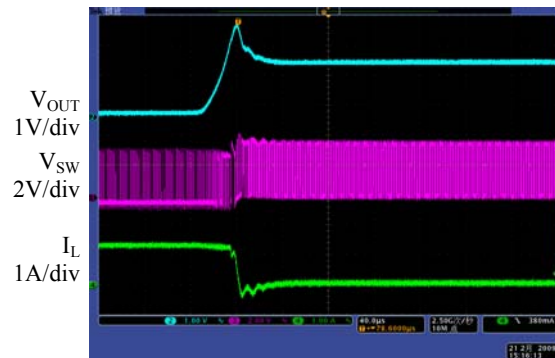
400μs/div

Figure 11. Start up from Shutdown
($V_{IN}=3.6V$, $V_{OUT}=1.8V$, $R_{LOAD}=2.5\Omega$)

1.1MHz, 800mA SYNCHRONOUS DC-DC BUCK CONVERTER AP3406A
Typical Performance Characteristics (Continued)


10µs/div

Figure 12. Short Circuit Protection
($V_{IN}=3.6V$, $V_{OUT}=1.8V$, no load)



40µs/div

Figure 13. Short Circuit Recovery
($V_{IN}=3.6V$, $V_{OUT}=1.8V$, no load)

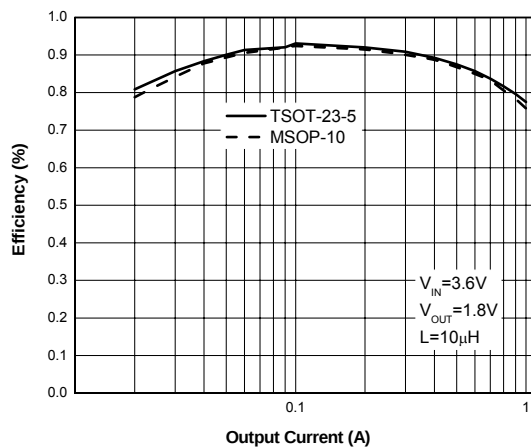


Figure 14. Efficiency vs. Output Current

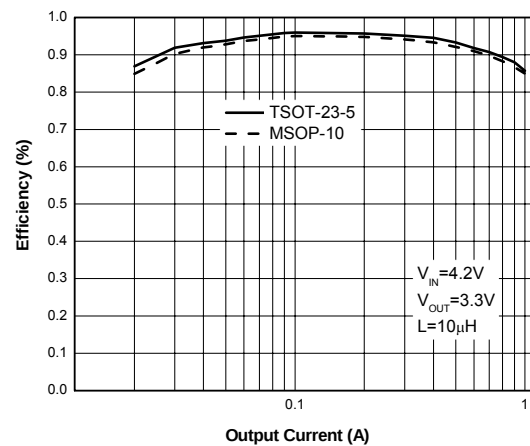


Figure 15. Efficiency vs. Output Current

1.1MHz, 800mA SYNCHRONOUS DC-DC BUCK CONVERTER AP3406A

Typical Performance Characteristics (Continued)

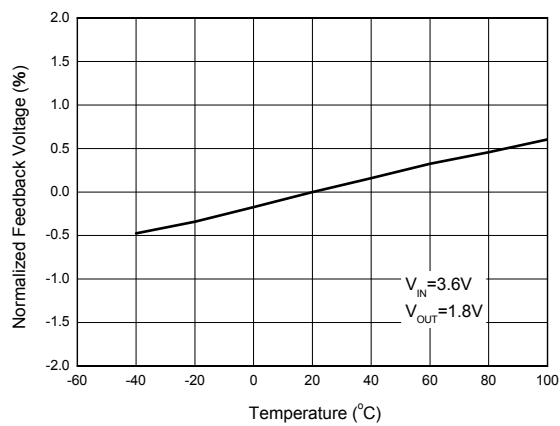


Figure 16. Normalized Feedback Voltage vs. Temperature

Typical Application

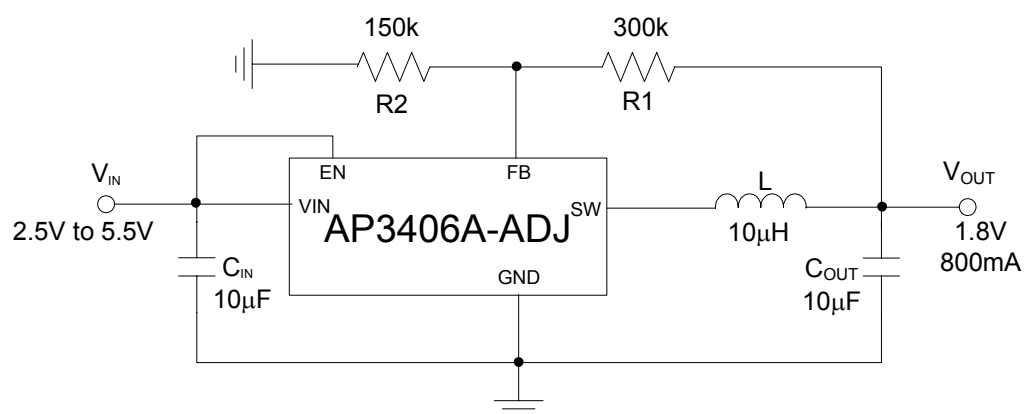


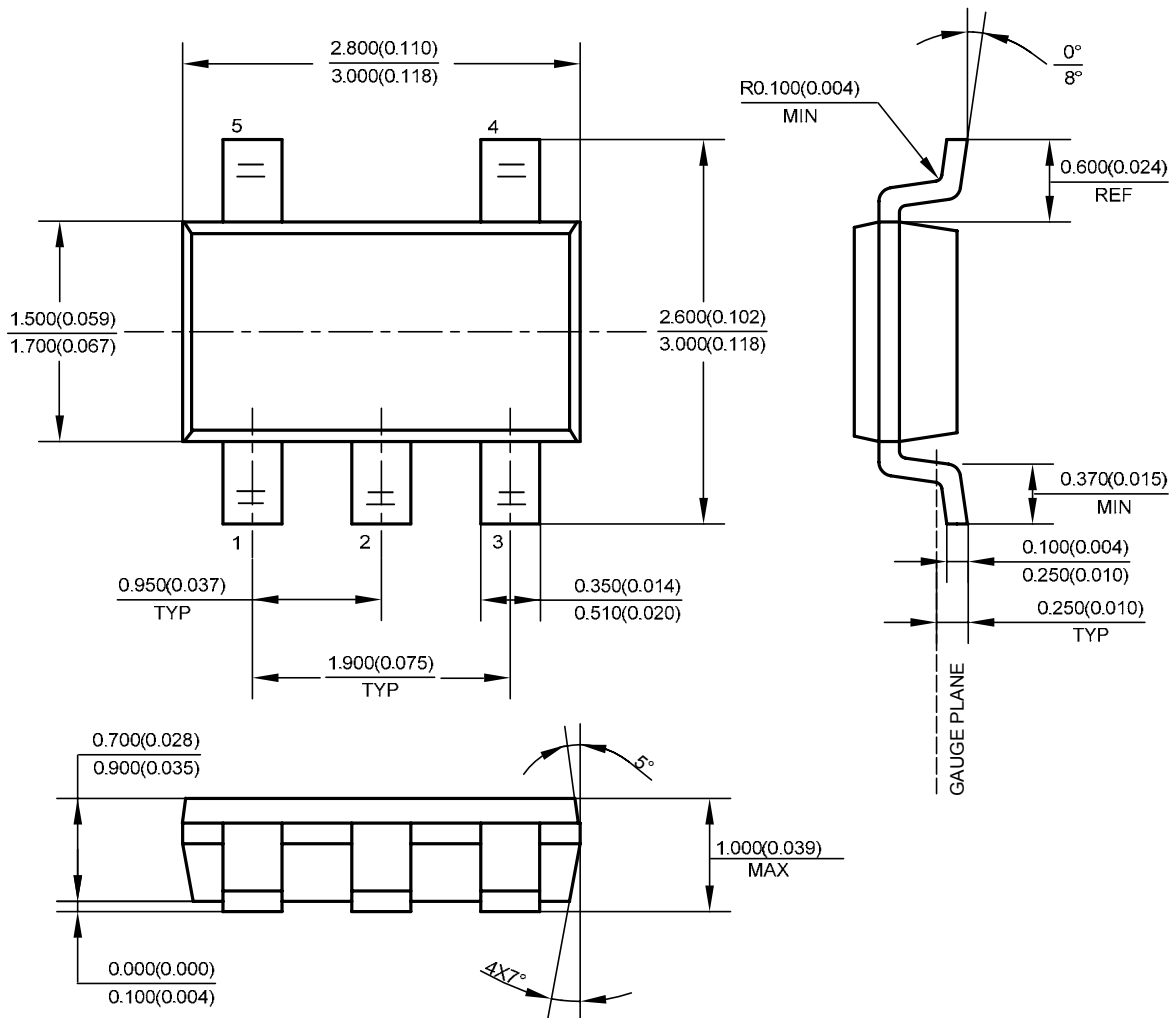
Figure 17. Typical Application of AP3406A

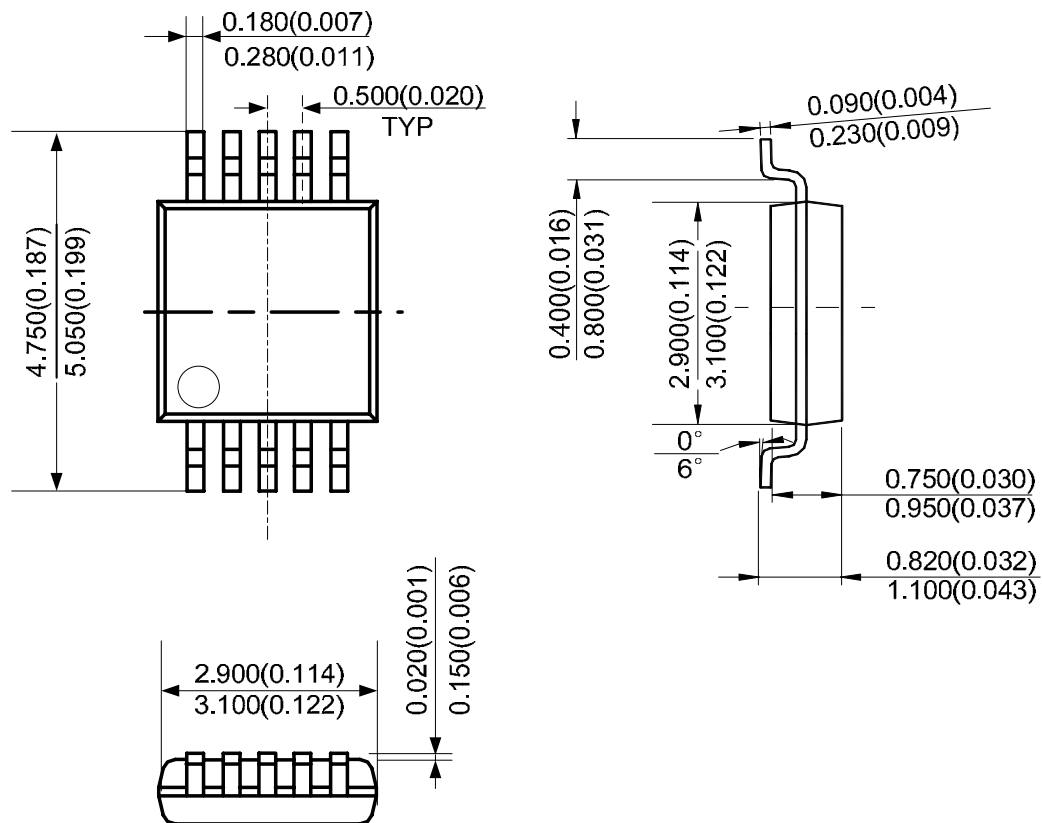
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Mechanical Dimensions

TSOT-23-5

Unit: mm(inch)



1.1MHz, 800mA SYNCHRONOUS DC-DC BUCK CONVERTER AP3406A
Mechanical Dimensions (Continued)
MSOP-10
Unit: mm(inch)


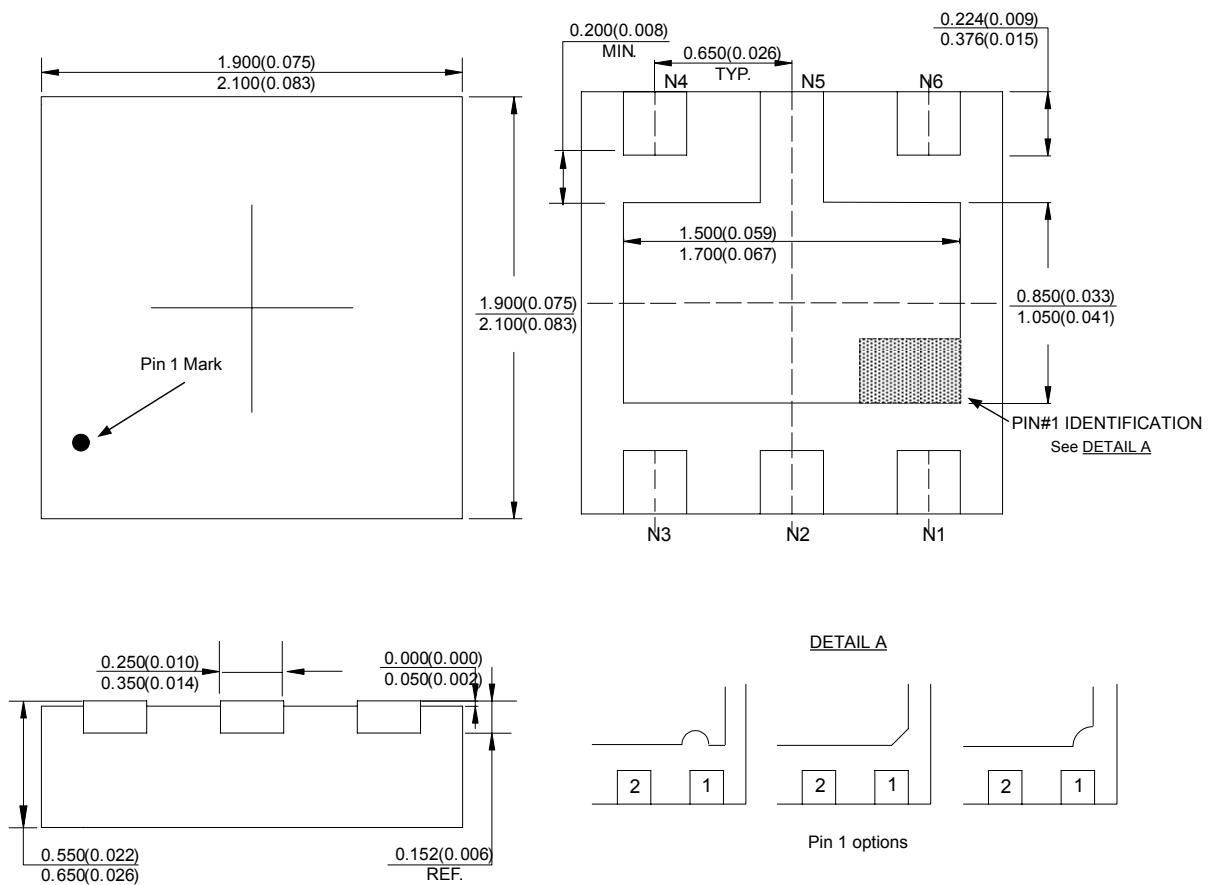
Note: Eject hole, oriented hole and mold mark is optional.

1.1MHz, 800mA SYNCHRONOUS DC-DC BUCK CONVERTER AP3406A

Mechanical Dimensions (Continued)

DFN-2×2-6(1)

Unit: mm(inch)





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